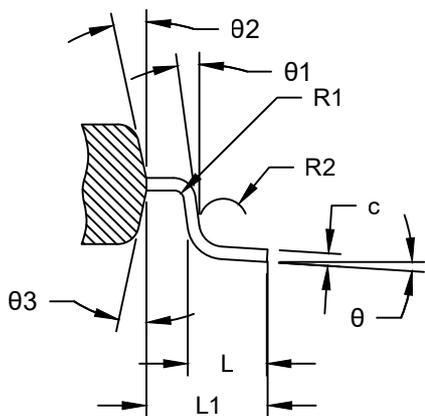
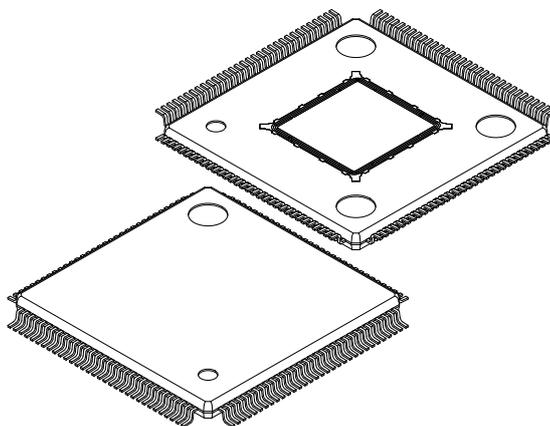


128-Lead Thin Quad Flat, Plastic (X9B) - 14x14x1 mm Body [TQFP] With 6.15x6.40 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



SECTION A-A



		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	128		
Lead Pitch	e	0.40 BSC		
Overall Height	A	-	-	1.20
Standoff	A1	0.05	0.10	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Length	D	16.00 BSC		
Molded Package Length	D1	14.00 BSC		
Exposed Pad Length	D2	6.05	6.15	6.25
Overall Width	E	16.00 BSC		
Molded Package Width	E1	14.00 BSC		
Exposed Pad Width	E2	6.30	6.40	6.50
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Lead Width	b	0.13	0.16	0.23
Lead Thickness	c	0.09	-	0.20
Lead Bend Radius	R1	0.08	-	-
Lead Bend Radius	R2	0.08	-	0.20
Lead Foot Angle	θ	0°	3.5°	7°
Lead Angle	$\theta 1$	0°	-	-
Mold Draft Angle Top	$\theta 2$	11°	12°	13°
Mold Draft Angle Bottom	$\theta 3$	11°	12°	13°

Notes:

- The Pin 1 visual index feature may vary, but it must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
REF: Reference Dimension, usually without tolerance, is for information purposes only.